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# Advanced Packaging Market Size, Share & Trends Analysis Report By Packaging Type (Flip-Chip, Fan-Out WLP, Embedded-Die, Fan-In WLP, 2.5D/3D), By Application (Consumer Electronics, Automotive, Industrial, Healthcare), By Region, And Segment Forecasts, 2025 - 2030

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## Abstracts

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Advanced Packaging Market Growth & Trends

The global advanced packaging market size is anticipated t%li%reach USD 55.00 billion by 2030 and is projected t%li%grow at a CAGR of 5.7% from 2025 t%li%2030, according t%li%a new report by Grand View Research, Inc. The market is experiencing robust growth primarily due t%li%the increasing demand for smaller, faster, and more energy-efficient electronic devices. As traditional Moore's Law scaling faces physical limitations, semiconductor manufacturers are turning t%li%advanced packaging technologies such as 2.5D/3D integration, fan-out wafer-level packaging (FOWLP), and system-in-package (SiP) solutions t%li%improve performance without shrinking transistor sizes. These technologies enable heterogeneous integration, allowing different types of chips t%li%be combined in a single package, which is crucial for applications in artificial intelligence, automotive electronics, and data centers.

The proliferation of Internet of Things (IoT) devices, smartphones, and wearable technology is another significant driver for advanced packaging solutions. These devices require compact form factors while maintaining high performance and low power consumption - demands that advanced packaging technologies are uniquely

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positioned t%li%address. Additionally, the automotive industry's shift toward electric vehicles and autonomous driving systems necessitates sophisticated semiconductor packages that can withstand harsh environments while delivering reliable performance, further accelerating market growth.

The emergence of 5G technology and high-performance computing applications represents another crucial catalyst for the advanced packaging sector. These technologies demand unprecedented levels of interconnect density, thermal management, and signal integrity that only advanced packaging solutions can provide. The ability t%li%integrate RF components, memory, and processors in tightly coupled packages is becoming essential for next-generation computing and communication systems, stimulating innovation and investment in packaging technologies.

Global supply chain diversification efforts following recent disruptions have als%li%contributed t%li%market expansion as countries and companies seek t%li%establish resilient semiconductor manufacturing ecosystems. This has led t%li%increased investment in advanced packaging facilities worldwide, with growth in Asia-Pacific regions. Furthermore, sustainability concerns are influencing packaging design choices, with manufacturers focusing on developing environmentally friendly materials and processes that reduce waste and energy consumption, aligning with broader industry trends toward green technology solutions.

Advanced Packaging Market Report Highlights

Based on packaging type, the flip chip segment accounted for the largest share, over 38.0% of the market in 2024. The embedded-die packaging type segment is expected t%li%grow at the fastest CAGR of 6.3% during the forecast period.

Based on application, the consumer electronics application segment dominated the advanced packaging market in 2024 by accounting for the largest revenue share of over 51.0%.

The automotive application segment is projected t%li%grow at the fastest CAGR of 6.3% over the forecast period of 2025 t%li%2030.

Asia Pacific dominated the market space by registering the largest revenue market share of over 43.0 in 2024 and is anticipated t%li%grow

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at the fastest CAGR of 6.2% during the forecast period.

In September 2024, Ont%li%Innovation Inc. announced the opening of its Packaging Applications Center of Excellence (PACE) in Wilmington, Massachusetts, marking a significant milestone in the advancement of panel-level packaging (PLP) technology. This first-of-its-kind facility in the U.S. is dedicated t%li%developing innovative PLP solutions that enable 2.5D and 3D chiplet architectures and AI packages.

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# Contents

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## CHAPTER 6. GLOBAL ADVANCED PACKAGING MARKET: REGION ESTIMATES & TREND ANALYSIS

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